Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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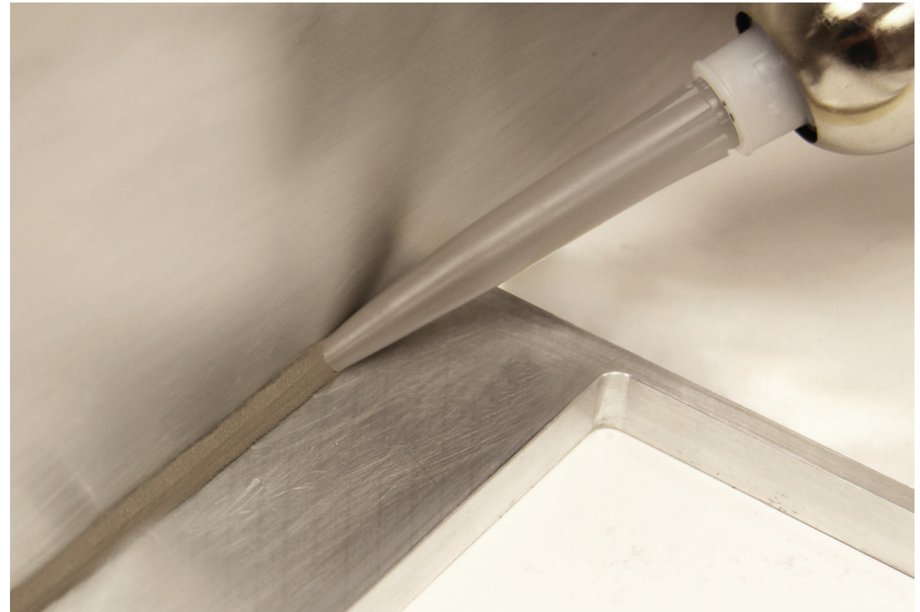
CHO-BOND® 1038 and 1121

ONE COMPONENT ELECTRICALLY CONDUCTIVE SILICONE SEALANT (1121 VOC FREE VERSION)

Customer Value Proposition:

CHO-BOND 1038 is a silver-plated copper filled, one-component conductive silicone. It is designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Minimum recommended bond line for CHO-BOND 1038 is 0.007 inches (0.18mm). In addition, CHO-BOND 1038 may be used for EMI gasket repair, bonding, and attachment in applications where moderate strength (less than 150 psi) is required. CHO-BOND 1038's moisture cure silicone polymer system allows it to cure to the touch in 24 hours and provides a robust conductive and environmental seal over a wide range of application temperatures. For applications requiring zero volatile organic compounds (VOCs) or minimal shrinkage, Parker Chomerics offers a solvent free version of CHO-BOND 1038 called CHO-BOND 1121.

For best adhesion results, CHO-BOND 1038 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters.



Features and Benefits:

- One component — Easy to use, no weighing or mixing required.
- Silver plated copper filler — Excellent conductivity 0.010 ohm-cm
- Moisture cure silicone — 30 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures. 1 week for full cure.
- Non corrosive cure mechanism — No corrosive by-products generated during curing to damage substrate.
- Medium paste — Easy to dispense, apply and spread, can be used on overhead or vertical surfaces.
- No VOCs version: CHO-BOND 1121 — Minimal shrinkage, no permits or ventilation required.

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CHO-BOND 1038 - Product Information

Table 1 Typical Properties

Typical Properties	Typical Values		Test Method	
	CHO-BOND 1038	CHO-BOND 1121		
Polymer	Silicone		N/A	
Filler	Silver-Plated Copper		N/A	
Mix Ratio, A : B (by weight)	1-part		N/A	
Color	Gray		N/A	(Q)
Consistency	Medium Paste		N/A	(Q)
Maximum DC Volume Resistivity	0.010 ohm-cm		CHO-95-40-5555*	(Q/C)
Minimum Lap Shear Strength**	150 psi (1034 kPa)		CHO-95-40-5300*	(Q/C)
Minimum Peel Strength**	4.0 lb./inch (700 N/m)		CHO-95-40-5302*	(Q/C)
Specific Gravity	3.6		ASTM D792	(Q/C)
Hardness	80 Shore A		ASTM-D2240	(Q/C)
Continuous Use Temperature	- 55°C to 125°C (-67 °F to 257 °F)		N/A	(Q)
Elevated Temperature Cure Cycle	None		N/A	
Room Temperature Cure	1 week***		N/A	(Q)
Working Life	0.5 hour		N/A	(Q)
Shelf Life, unopened	6 months @ 25°C (77°F)	12 months @ 25°C (77°F)	N/A	(Q)
Minimum thickness recommended	0.007 in (0.18 mm)		N/A	
Maximum thickness recommended	0.125 in (3.18 mm)		N/A	
Volatile Organic Content (VOC)	111 g/l	0 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	775 in² (5000 cm²)		N/A	
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	50 feet (15.2 m)		N/A	

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.
** Minimum values listed are based on using the CHO-SHIELD 1086 primer that typically comes bundled with the CHO-BOND.
*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1038	113.4	1.5 fluid ounce aluminum foil tube	50-02-1038-0000	1086
	113.4	1.5 fluid ounce aluminum foil tube	50-02-1038-1000	No
	227	2.5 fluid ounce SEMCO cartridge	50-33-1038-0000	No
	454	6 fluid ounce SEMCO cartridge	50-01-1038-0000	1086
	454	6 fluid ounce SEMCO cartridge	50-31-1038-0000	No
CHO-BOND 1121	454	6 fluid ounce SEMCO cartridge	50-01-1121-0000	1086

Note: Supplied in a plastic 6 fluid ounce cartridge suitable for standard air-operated caulking guns. To achieve maximum shelf life/pot life, caulking gun should be activated with dry bottled nitrogen.

Table 3 Primer Ordering Information

Product	Weight (grams)	Packaging	Part Number
CHO-BOND 1086	10	3 dram glass vial	50-10-1086-0000
	95	4 fluid ounce glass bottle	50-04-1086-0000
	375	1 pint can	50-01-1086-0000

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

www.chomerics.com
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